

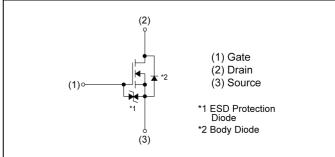
RJ1P12BBD

Nch 100V 120A Power MOSFET

| V _{DSS} | 100V |
|----------------------------|-------|
| R _{DS(on)} (Max.) | 5.8mΩ |
| Ι _D | ±120A |
| P _D | 178W |

Outline TO-263AB (2)LPT(L)

Inner circuit



Packaging specifications

| Туре | Packing | Embossed Tape |
|------|-----------------|------------------|
| | Reel size (mm) | 330 |
| | Tape width (mm) | 24 |
| | Quantity (pcs) | 1000 |
| | Taping code | TLL |
| | Marking | RJ1P12BBD |

● Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

| U (a | | • / | | |
|--|------------------------------|-------------------|------|---|
| Parameter | Symbol | Value | Unit | |
| Drain - Source voltage | | V _{DSS} | 100 | V |
| Continuous drain current V _{GS} = 10V | | ۱ _D *1 | ±120 | А |
| Pulsed drain current | ا _{DP} *2 | ±240 | А | |
| Gate - Source voltage | V _{GSS} | ±20 | V | |
| Avalanche current, single pulse | I _{AS} *3 | 40 | А | |
| Avalanche energy, single pulse | E _{AS} *3 | 125 | mJ | |
| Power dissipation | P _D ^{*1} | 178 | W | |
| Junction temperature | Tj | 150 | C° | |
| Operating junction and storage temper | T _{stg} | -55 to +150 | C° | |

5) Halogen free

1) Low on - resistance

2) High power small mold package

3) Pb-free lead plating ; RoHS compliant

Application

Features

4) UIS tested

Switching

•Thermal resistance

| Parameter | Symbol | Values | | | Linit |
|-------------------------------------|-----------------|--------|------|------|-------|
| Farameter | Symbol | Min. | Тур. | Max. | Unit |
| Thermal resistance, junction - case | R_{thJC}^{*1} | - | - | 0.70 | °C/W |

•Electrical characteristics (T_a = 25°C)

| Demonster | Oursela e l | Q and l'it's and | Values | | | | |
|--|---|---|--------|-------|------|-------|--|
| Parameter | Symbol Conditions | | Min. | Тур. | Max. | Unit | |
| Drain - Source breakdown voltage | $V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$ | | 100 | - | - | V | |
| Breakdown voltage temperature coefficient | $\frac{\Delta V_{(BR)DSS}}{\Delta T_{i}} I_{D} = 1 \text{mA}$ | | - | 98.33 | - | mV/°C | |
| Zero gate voltage drain current | I_{DSS} V_{DS} = 100V, V_{GS} = 0V | | - | - | 10 | μA | |
| Gate - Source leakage current | I _{GSS} | I_{GSS} $V_{GS} = \pm 20V, V_{DS} = 0V$ | | - | ±10 | μA | |
| Gate threshold voltage | $V_{GS(th)}$ | V _{DS} = 10V, I _D = 2.5mA | 2.0 | - | 4.0 | V | |
| Gate threshold voltage temperature coefficient | $\frac{\Delta V_{GS(th)}}{\Delta T_j}$ | | | -8.28 | - | mV/°C | |
| Static drain - source | D *4 | V _{GS} = 10V, I _D = 50A | - | 4.4 | 5.8 | | |
| on - state resistance | $R_{DS(on)}^{*4}$ | V _{GS} = 6.0V, I _D = 40A | - | 5.2 | 7.8 | mΩ | |
| Gate resistance | R _G | R_G f = 1MHz, open drain | | 2.6 | - | Ω | |
| Forward Transfer Admittance | Y _{fs} ^{*4} | V _{DS} = 5V, I _D = 40A | 30 | - | - | S | |

*1 T_c =25°C, Limited only by maximum temperature allowed.

*2 Pw \leq 10µs , Duty cycle \leq 1%

*3 L \simeq 0.10mH, V_{DD} = 50V, R_G = 25 Ω , Starting T_j = 25°C Fig.3-1,3-2

*4 Pulsed



•Electrical characteristics (T_a = 25°C)

| Deremeter | Cumphal | Conditions | | Unit | | |
|------------------------------|------------------------|-----------------------------------|---|------|------|------|
| Parameter | Symbol | /mbol Conditions | | Тур. | Max. | Unit |
| Input capacitance | C _{iss} | V _{GS} = 0V | - | 4170 | - | |
| Output capacitance | C _{oss} | V _{DS} = 50V | - | 590 | - | pF |
| Reverse transfer capacitance | C _{rss} | C _{rss} f = 1MHz | | 130 | - | |
| Turn - on delay time | t _{d(on)} *4 | $V_{DD} \simeq 50V, V_{GS}$ = 10V | - | 37 | - | |
| Rise time | t _r *4 | I _D = 50A | - | 33 | - | |
| Turn - off delay time | t _{d(off)} *4 | $R_L \simeq 1.0\Omega$ | - | 125 | - | ns |
| Fall time | t _f *4 | R _G = 10Ω | - | 54 | - | |

• Gate charge characteristics ($T_a = 25^{\circ}C$)

| Deremeter | Sumbol | ymbol Conditions | | Values | | | 1 1 | |
|--------------------------|--------------------|----------------------|-----------------------|--------|------|------|------|----|
| Parameter | Symbol | | | Min. | Тур. | Max. | Unit | |
| Tatal water channel 0 *4 | O *4 | | V _{GS} = 10V | - | 80.0 | - | | |
| Total gate charge | Q _g *4 | $V_{DD} \simeq 50V$ | $V_{DD} \simeq 50V$ | | - | 51.0 | - | nC |
| Gate - Source charge | Q _{gs} *4 | I _D = 50A | V _{GS} = 6V | - | 24.0 | - | nc | |
| Gate - Drain charge | Q _{gd} *4 | | | - | 17.5 | - | | |

•Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

| Deremeter | Symbol | | Values | | | Unit |
|----------------------------|--------------------|--|--------|------|------|------|
| Parameter | Symbol | ymbol Conditions | | Тур. | Max. | Unit |
| Continuous forward current | I _S | T _a = 25°C | - | - | 120 | А |
| Pulse forward current | I _{SP} *2 | $T_a = 25 C$ | - | - | 240 | А |
| Forward voltage | V _{SD} *4 | V _{GS} = 0V, I _S = 40A | - | - | 1.2 | V |
| Reverse recovery time | t _{rr} *4 | I _S = 50A, V _{GS} =0V | - | 67 | - | ns |
| Reverse recovery charge | Q _{rr} *4 | di/dt = 100A/µs | - | 225 | - | nC |



1000

= 10ms

P

100

10/

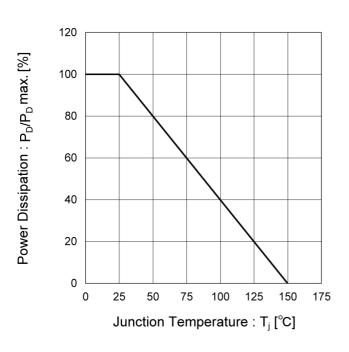


Fig.1 Power Dissipation Derating Curve

1000 1000 100 100 10 $P_{W} = 100\mu s$

Drain Current : I_D [A]

1

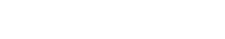
0.1

0.1

T_a=25°C Single Pulse

1

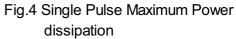
Fig.2 Maximum Safe Operating Area

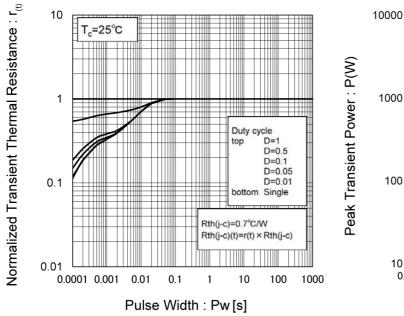


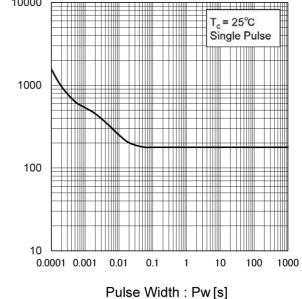
10

Drain - Source Voltage : V_{DS} [V]

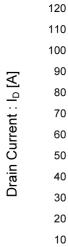
Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width











0

0

Fig.5 Typical Output Characteristics(I)

T_a=25°C

1

Pulsed

V_{GS}= 10V

V_{GS}= 6.0V

 $V_{GS} = 4.5V$

 $V_{GS} = 4.0V$

0.1 0.2 0.3 0.4 0.5 0.6 0.7 0.8 0.9

Drain - Source Voltage : V_{DS} [V]

Fig.6 Typical Output Characteristics(II)

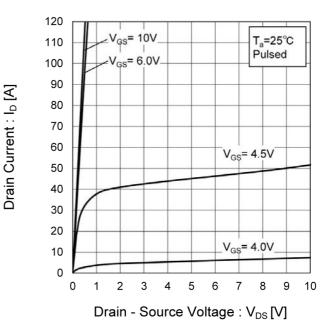
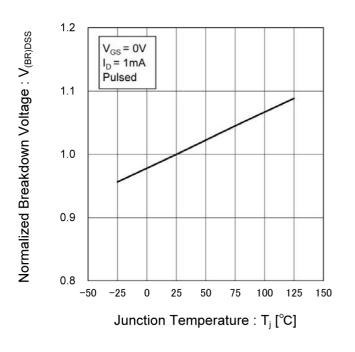


Fig.7 Breakdown Voltage vs. Junction Temperature







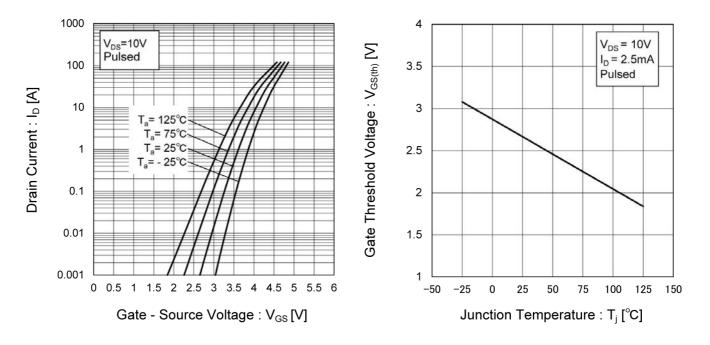
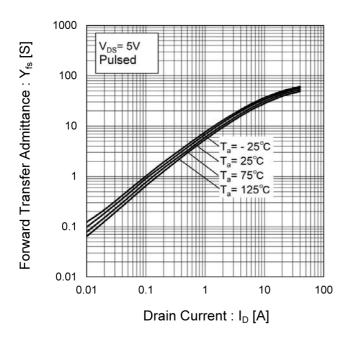


Fig.8 Typical Transfer Characteristics

Fig.9 Gate Threshold Voltage vs. Junction Temperature

Fig.10 Forward Transfer Admittance vs. Drain Current







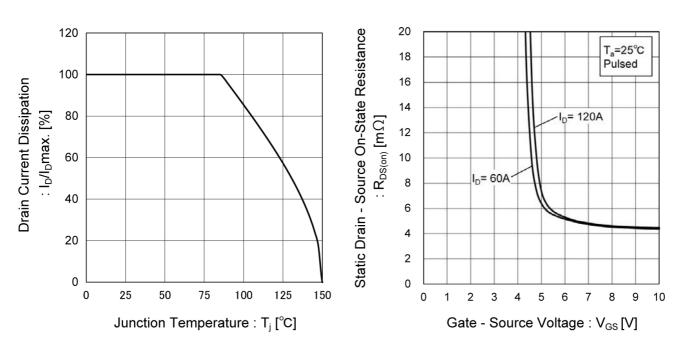
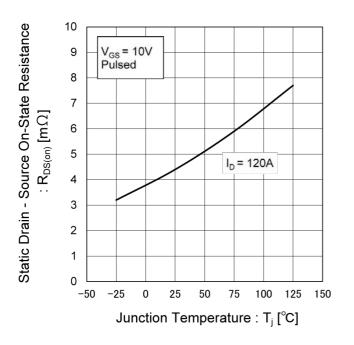


Fig.11 Drain Current Derating Curve

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature







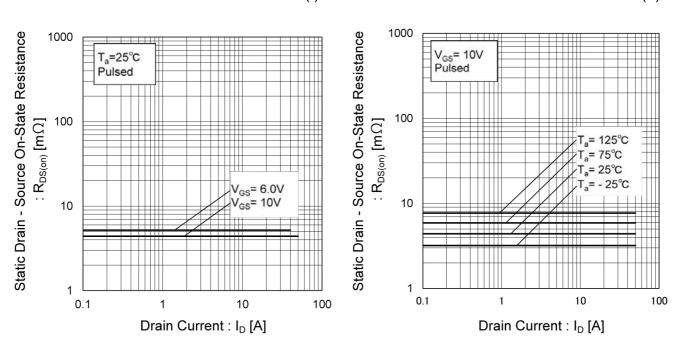
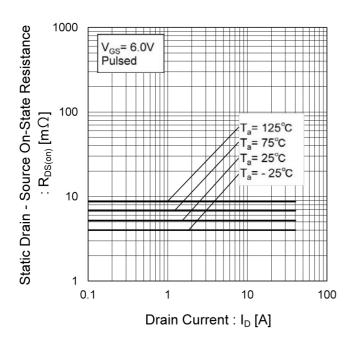


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I) Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)







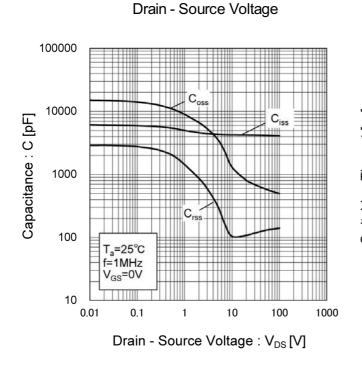


Fig.17 Typical Capacitance vs.

Fig.18 Switching Characteristics

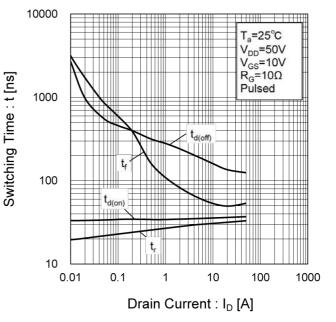


Fig.19 Dynamic Input Characteristics

Gate - Source Voltage : V_{GS} [V]

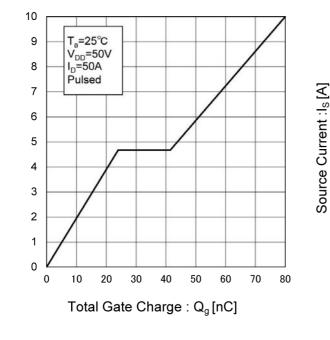
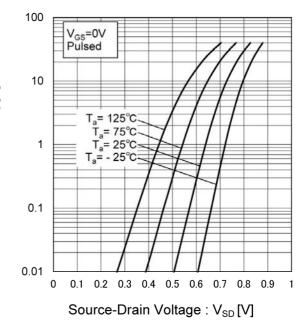


Fig.20 Source Current vs. Source Drain Voltage





Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

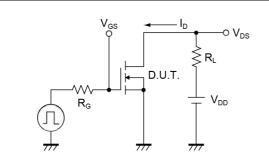


Fig.2-1 Gate Charge Measurement Circuit

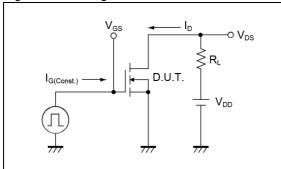


Fig.3-1 Avalanche Measurement Circuit

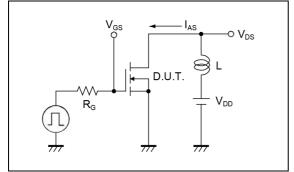


Fig.1-2 Switching Waveforms

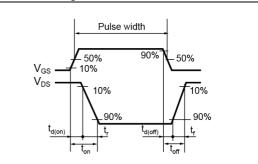


Fig.2-2 Gate Charge Waveform

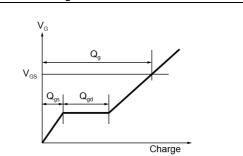
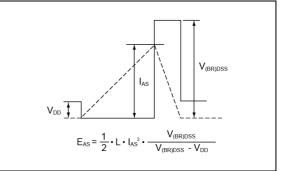
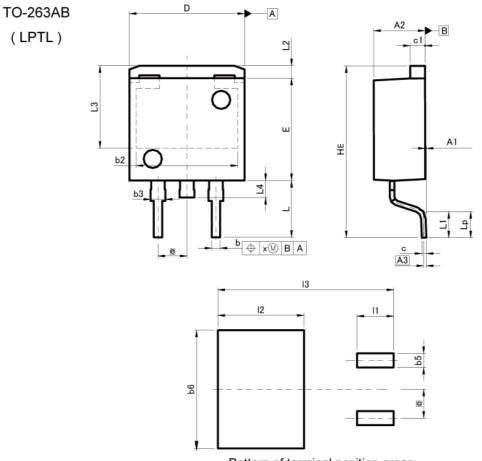


Fig.3-2 Avalanche Waveform





Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

| DIM | MILIMETERS | | INC | HES |
|-----|-----------------|-------|-------|-------|
| | MIN | MAX | MIN | MAX |
| A1 | 0.00 | 0.30 | 0.000 | 0.012 |
| A2 | 4.30 | 4.70 | 0.169 | 0.185 |
| A3 | 0.: | 25 | 0.0 | 10 |
| b | 0.68 | 0.98 | 0.027 | 0.039 |
| b2 | 8.9 | 90 | 0.3 | |
| b3 | 1.14 | 1.44 | 0.045 | 0.057 |
| С | 0.30 | 0.60 | 0.012 | 0.024 |
| c1 | 1.10 | 1.50 | 0.043 | 0.059 |
| D | 9.80 | 10.40 | 0.386 | 0.409 |
| E | 8.80 | 9.20 | 0.346 | 0.362 |
| e | 2.5 | 54 | 0.1 | 00 |
| HE | 14.80 | 15.40 | 0.583 | 0.606 |
| L | 4.70 | 5.30 | 0.185 | 0.209 |
| L1 | 2.10 | 2.70 | 0.083 | 0.106 |
| L2 | 1. | 10 | 0.043 | |
| L3 | 7.1 | 7.25 | | 85 |
| L4 | 1.5 | 1,50 | | 59 |
| Lp | 2.60 | 2.00 | 0.102 | 0.079 |
| x | 1 | 0.25 | - | 0.010 |
| | MILIM | TERS | INC | HES |
| DIM | MIN | MAX | MIN | MAX |
| b5 | - | 1.23 | - | 0.049 |
| b6 | | 10.40 | | 0,409 |
| 11 | 1 | 3.20 | | 0.126 |
| 12 | 2 73 | 7.55 | - | 0.297 |
| 13 | 5 | 15.40 | - | 0.606 |

Dimension in mm/inches



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| (Note1) Medical Equipment Classification of the Specific Applications |
|---|
|---|

| JAPAN | USA | EU | CHINA |
|--------|---------|------------|---------|
| CLASSⅢ | CLASSI | CLASS II b | CLASSII |
| CLASSⅣ | CLASSII | CLASSⅢ | CLASSI |

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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
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 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
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- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
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- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
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